

TFT LCD Display Specification

PN: GLT035320240TR2

Overview:

- 3.5" Diagonal
- View angle 12 O'clock
- Driver: NV3035GTC
- 16.7M Colors
- 320 Nits

- 320 x 240 Pixels
- Transmissive/Normally Black
- RGB-24bit+SPI Interface
- No Touch Panel
- RoHS Compliant

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Records of Revision

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2018-04-13		V01	First Issue	
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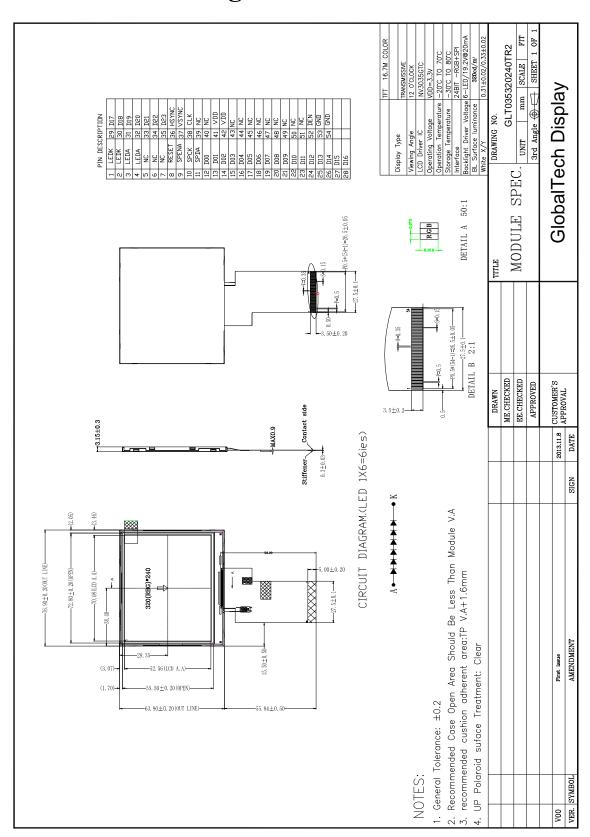
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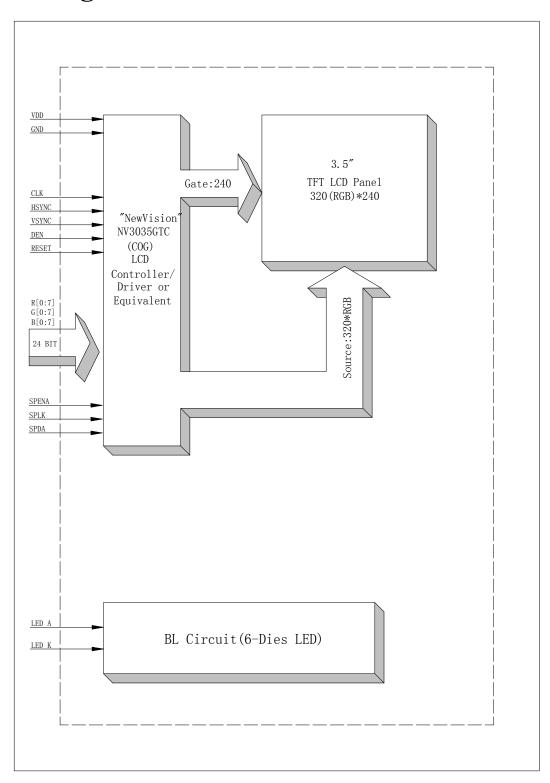
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	76.90*63.90*3.15	MM
ACTIVE SIZE (W*H)	70.08*52.56	MM
PIXEL PITCH (W*H)	0.219*0.219	MM
NUMBER OF DOTS	320*240	
DIVER IC	NV3035GTC	
INTERFACE TYPE	24BIT RGB+SPI	
TOP POLARIZER TYPE	GLARE	
RECOMMEND VIEWING DIRECTION	12	O'CLOCK
GRAY SCALE INVERSION DIRECTION	6	O'CLOCK
COLORS	16.7M	
BACKLIGHT TYPE	6-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3.Block Diagram



4.Interface Pin Function

Pin No.	Symbol	Description
1	LEDK	Cathode of LED backlight
2	LEDK	Cathode of LED backlight
3	LEDA	Anode of LED backlight
4	LEDA	Anode of LED backlight
5	NC	No connect
6	NC	No connect
7	NC	No connect
8	RESET	RESET PIN
9	SPENA	Chip select of serial interface
10	SPCLK	Clock pin of serial interface
11	SPDA	Serial data input
12~35	D00~D23	Data bus
36	HSYNC	Horizontal sync signal
37	VSYNC	Vertical sync signal
38	DCLK	Clock signal; latching data at the falling edge
39	NC	No connect
40	NC	No connect
41	VDD	Power supply
42	VDD	Power supply
43~51	NC	No connect
52	DEN	Data enable
53	GND	Ground
54	GND	Ground

5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.5	V
Supply voltage for logic	VDD	-0.3	4.5	V
Supply current (One LED)	I_{LED}		30	mA
Operating temperature	T_{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute Data enable maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6.Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	3.0	3.3	3.6	V	
Supply Voltage for Logic	VDD	3.0	3.3	3.6	V	
Innut Waltaga	$V_{\rm IL}$	GND	-	0.3VDD	V	
Input Voltage	$ m V_{IH}$	0.7 VDD	-	VDD	V	
Input leakage Current	I_{LKG}	-1		1	μА	

6.2 Backlight Driving Conditions

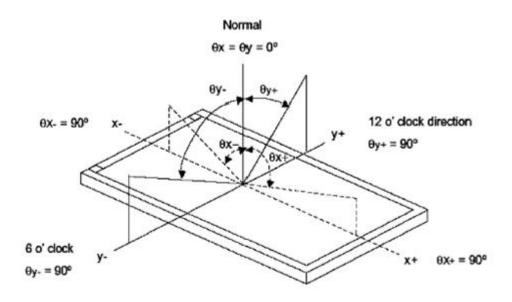
Itama	Cross had		Value	Unit	Remar	
Item	Symbol	Min.	Тур.	Max.	Unit	k
Voltage for LED Backlight	V _F	-	19.2	-	V	I _L =20mA
Current for LED Backlight	IL		20		mA	
Power Consumption	P		0.384		W	
LED Life Time		30,000	50,000		Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}$ C

7. Optical Characteristics

IODA		CVADOL	COMPLETIONS	SPEC	IFICA	ΓΙΟΝS	TINITE	NOTE	
ITEN	/1	SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT	NOTE	
Lumina	nce	L	I _L =20mA		320		Cd/m ²	Note 4	
Contrast l	Ratio	CR	θ=0°	400	500			Note 2	
Dagnanga	Time	Ton	25℃		20	30	100 G	Note 2	
Response	Time	Toff	23 C		20	30	ms	Note 3	
	Red	XR			0.5934				
	Red	YR			0.3436				
	Green	XG			0.3340				
CIE Color	Green	YG	Viewing normal		0.5923				
Coordinate	DI	Хв	angle		0.1413				
	Blue	Yв			0.0806				
	White	Xw			0.3114				
	winte	Yw			0.3327				
	Hor.	$ heta_{\scriptscriptstyle X+}$		60	70				
Viewing	пог.	$ heta_{\scriptscriptstyle X-}$	CR≥10	60	70		Dagga	Note 1	
Angle	Vor	$ heta_{\scriptscriptstyle Y+}$	CK≥10	50	60		Degree		
	Ver.	$ heta_{\scriptscriptstyle Y}$		60	70				
Uniformity	Un			75	80		%		

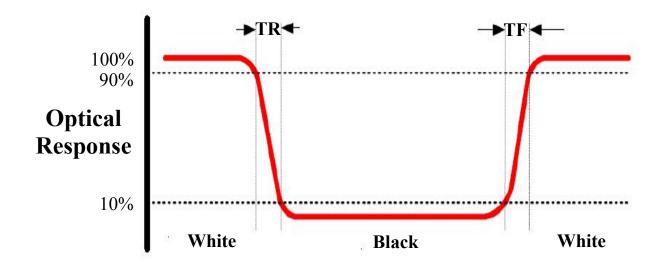
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance\ of\ white\ state}{Luminance\ of\ black\ state}$$

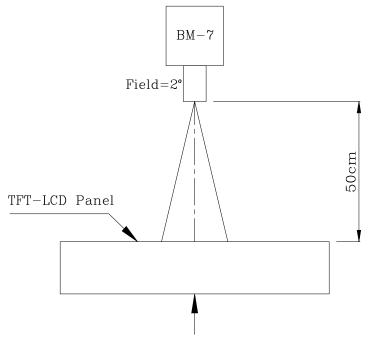
Note 3: Definition of Response Time(Tr,Tf)



Note 4: Definition of Luminance

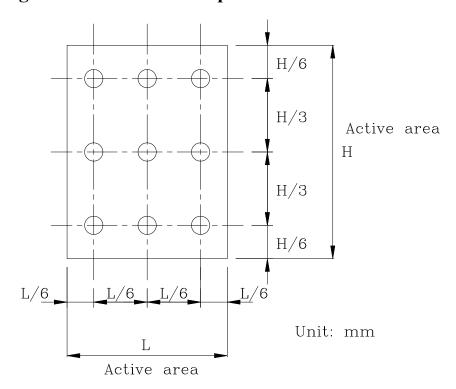
①The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



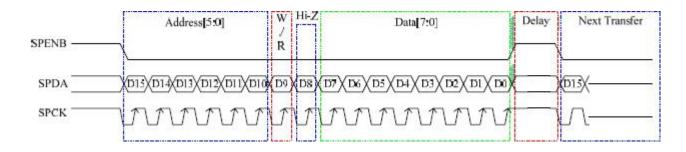
The center of the screen

②The Brightness Test Point Setup



8. Timing Characteristics

8.1 3-wire SPI Timing Diagram



3-Wire Command Format:

Bit	Description
D15-D10	Register Address [5:0]
D9	W/R control bit. "1" for Write, "0" for Read
D8	Hi-Z bit during read mode. Any data within this bits will be ignored during write mode
D7-D0	Data for the WR operation to the address indicated by Address phase

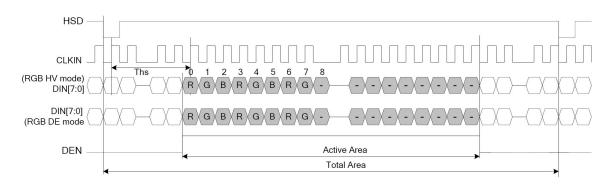
3-Wire Writer Format:

MSB			4			V 35		(6) (7)			0:	LS	В		(2)
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Register Address [5:0] 1 X DATA (Issue by external controller)															

3-Wire Read Format:

MSB												LSB			
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	Register Address [5:0]						Hi-Z			DATA	(Issue	by NV	3035C)	

8.2 Input data format

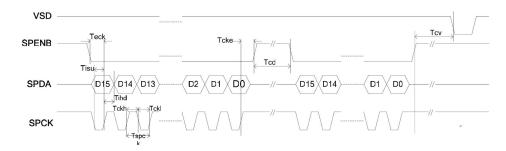


Input Format	Format Standard	CLKIN(MHz)	HSD(CLKIN)	Total Area (CLKIN)	Active Area (CLKIN)	Note
8bit RGB	8bit RGB	27	1	1716	960	960×240
24bit RGB	24bit RGB	6.4	1	408	320	

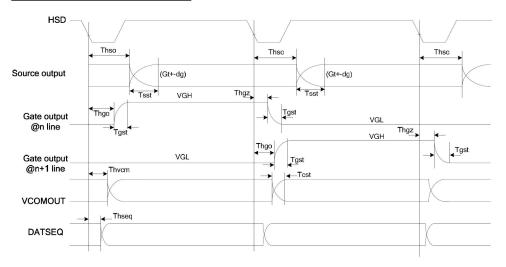
Clock and Data Input Timing Diagram Tclk Tcwh Tcwl CLKIN First Tdsu Tdhd DIN[7:0] First data 2nd data Last data DEN [≺]Tesu</sub>≻ CLKIN Tvhd Tvst VSD Thwh Thhd HSD Thst CLKIN Last DIN[7:0] Last-1 data Last data Thc HSD

8.3 Timing Diagram

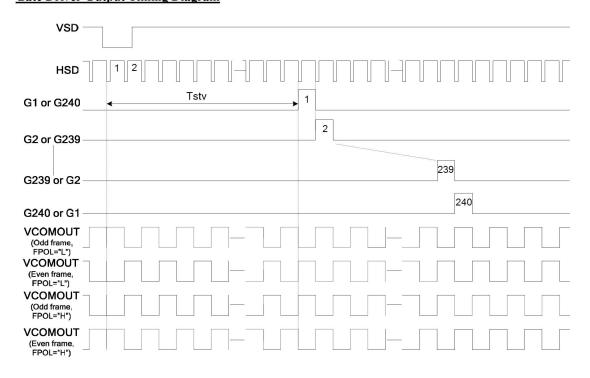
3-Wire Timing Diagram



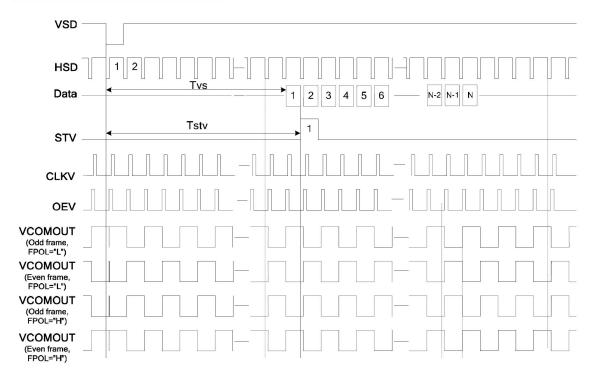
Source Driver Output Timing Diagram



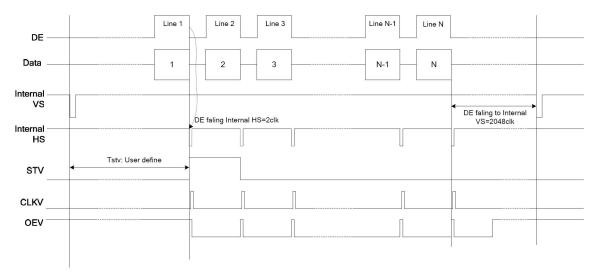
Gate Driver Output Timing Diagram



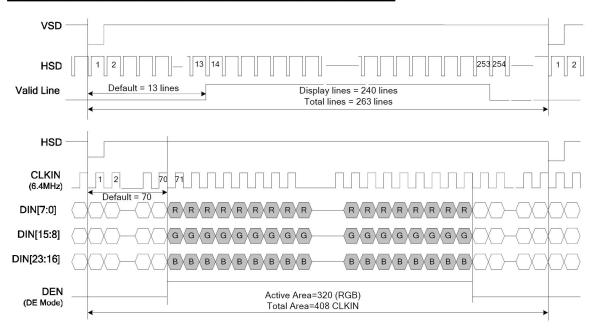
Vertical Timing Diagram (HV Mode)



Vertical Timing Diagram (DE Mode)



Input Data Timing (24 bit RGB mode for 960×240 @ SEL[3:0]=1100b)



9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
00	Electrical	Air: $\pm 4KV 150pF/330\Omega 5$ times
09	Static Discharge	Contact: ±2KV 150pF/330Ω 5 time

^{*}Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by GlobalTech Dispaly.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

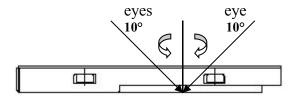
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

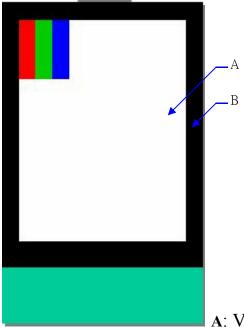
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item		Cri	terion		AQL
01	Electrical Testing	1.1 Missing vertical, hori 1.2 Missing character, do 1.3 Display malfunction. 1.4 No function or no dis 1.5 Current consumption 1.6 LCD viewing angle d 1.7 Mixed product types. 1.8 Flicker	lot or icon. i. isplay. n exceeds p defect.	· · ·		0.65
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or of Five spots. 2.2 Densely spaced: No	-			2.5
ospots, white spots,	Touch Panel black	3.1 Round type: As follows: $\Phi = (X+Y)/2$ * Densely spaced: No		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm.	2.5
	spots, contaminati on (non –	3.2 Line type: (As follows with the foll	Length(mm) L≤3.0 L≤2.5	mg) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense	2.5

NO.	Item	Crit	terion		AQL
		If bubbles are visible,	Size Φ(mm)	Acceptable Q'ty	
0.4	Polarizer	judge using black spot specifications, not easy	Φ≦0.20	Accept no dense	2.5
04	bubbles	to find, must check in	$0.20 < \Phi \leq 0.50$	3	2.5
		specify direction	$0.50 < \Phi \le 1.00$	2	
			1.00< Φ	0	_
			Total Q'ty	3	_
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass		x: Chip length $x \le 1/8a$ $x \le 1/8a$ The total length of each $x \le 1/8a$	chip	2.5

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm}$ $x \le 1/8 a$ $0 < z \le t$	
		7.2.2 Non-conductive portion:	
07	Glass crack	y z z z z z z z z z z z z z z z z z z z	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack 	
		y: width x: length	
		$y \le 1/3L \qquad X \le a$	

NO.	Item		Criterion		AQL
14	Touch Panel Chipped glass	k: Seal width t: 'L: Electrode pad length 14.1 General glass class clas	y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length x≤ 1/8a	
		z: Chip thickness	y: Chip width	x: Chip length	
		z≦t	≤ 1/2 k and not over viewing area	x ≤ 1/8a	
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip	

NO.	Item	Criterion	AQL
15	Touch Panel(Fish eye dent and bubble on film)	SIZE(mm)Acceptable Q'ty $\Phi \le 0.2$ Accept no dense $0.2 < D \le 0.4$ 5 $0.4 < D \le 0.5$ 2 $0.5 < D$ 0	2.5
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12.Packing Method

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